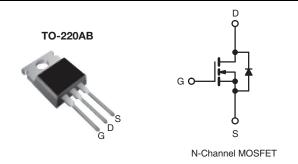


Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	100			
R _{DS(on)} (Ω)	$V_{GS} = 5.0 \text{ V}$	0.27		
Q _g (Max.) (nC)	12			
Q _{gs} (nC)	3.0			
Q _{gd} (nC)	7.1			
Configuration	Single			



FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Logic-Level Gate Drive
- R_{DS(on)} Specified at V_{GS} = 4 V and 5 V
- 175 °C Operating Temperature
- Fast Switching
- · Ease of Paralleling
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRL520PbF
Leau (FD)-iree	SiHL520-E3
SnPb	IRL520
SIFD	SiHL520

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	100	V	
Gate-Source Voltage	V_{GS}	± 10	V	
Continuous Drain Current	V_{GS} at 5.0 V $T_C = 25 ^{\circ}C$	I _D	9.2	
Continuous Drain Current	V_{GS} at 5.0 $V_{C} = 100 ^{\circ}C$		6.5	Α
Pulsed Drain Current ^a	I _{DM}	36		
Linear Derating Factor		0.40	W/°C	
Single Pulse Avalanche Energy ^b	E _{AS}	170	mJ	
Avalanche Current ^a	I _{AR}	9.2	А	
Repetitive Avalanche Energya	E _{AR}	6.0	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$		P_{D}	60	W
Peak Diode Recovery dV/dt ^c	dV/dt	5.5	V/ns	
Operating Junction and Storage Temperature Rang	T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s	-	300 ^d	
Mounting Torque	6-32 or M3 screw		10	lbf ⋅ in
Mounting Torque	0-32 OF IVIS SCIEW		1.1	N⋅m

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. $V_{DD} = 25 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 3.0 \, \text{mH}$, $R_q = 25 \, \Omega$, $I_{AS} = 9.2 \, \text{A}$ (see fig. 12).
- c. $I_{SD} \le 9.2 \text{ A}$, $dI/dt \le 110 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_{J} \le 175 \,^{\circ}\text{C}$.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Case-to-Sink, Flat, Greasd Surface	R _{thCS}	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	2.5		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	100	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.12	-	V/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	1.0	-	2.0	V	
Gate-Source Leakage	I _{GSS}	,	V _{GS} = ± 10 V	-	-	± 100	nA	
Zoro Coto Voltago Drain Current	I _{DSS}	V _{DS} =	V _{DS} = 100 V, V _{GS} = 0 V		-	25	μА	
Zero Gate Voltage Drain Current		$V_{DS} = 80 \text{ V}$	V _{DS} = 80 V, V _{GS} = 0 V, T _J = 150 °C		-	250		
Drain Source On State Registance	D	V _{GS} = 5.0 V	I _D = 5.5 A ^b	-	-	0.27	Ω	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 4.0 V	I _D = 4.6 A ^b	-	-	0.38		
Forward Transconductance	9 _{fs}	V _{DS} :	= 50 V, I _D = 5.5 A	3.2	-	-	S	
Dynamic								
Input Capacitance	C_{iss}		$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz, see fig. 5}$		490	-	pF	
Output Capacitance	Coss				150	-		
Reverse Transfer Capacitance	C_{rss}	t = 1.			30	-		
Total Gate Charge	Q_g			-	-	12		
Gate-Source Charge	Q_{gs}	$V_{GS} = 5.0 \text{ V}$	$V_{GS} = 5.0 \text{ V}$ $I_D = 9.2 \text{ A, } V_{DS} = 80 \text{ V,}$ see fig. 6 and 13 ^b		-	3.0	nC	
Gate-Drain Charge	Q_{gd}				-	7.1		
Turn-On Delay Time	t _{d(on)}			-	9.8	-		
Rise Time	t _r	V_{DD} = 50 V, I_{D} = 9.2 A, R_{g} = 9.0 Ω , R_{D} = 5.2 Ω , see fig. 10 ^b		-	64	-	ns	
Turn-Off Delay Time	$t_{d(off)}$			-	21	-		
Fall Time	t _f			-	27	-		
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH	
Internal Source Inductance	L _S			-	7.5	1	11111	
Drain-Source Body Diode Characteristic	s							
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	9.2	A	
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction diode		-	_	36		
Body Diode Voltage	V_{SD}	T _J = 25 °C	$T_J = 25 ^{\circ}\text{C}, I_S = 9.2 \text{A}, V_{GS} = 0 \text{V}^{\text{b}}$		-	2.5	V	
Body Diode Reverse Recovery Time	t _{rr}	T 25 °C 1	- 0.2 A dl/dt = 100 A/web	-	130	190	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = 9.2 \text{A}, dI/dt = 100 \text{A/} \mu \text{s}^{\text{b}}$		-	0.83	1.0	μC	
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300~\mu s;$ duty cycle $\leq 2~\%.$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

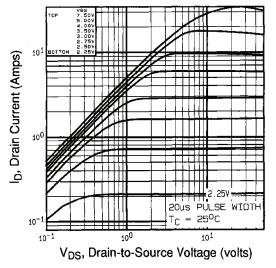


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

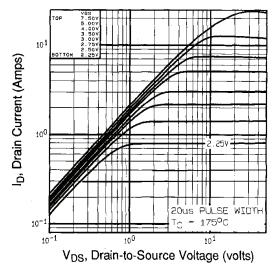


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

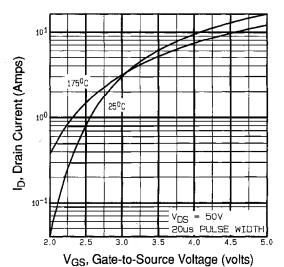


Fig. 3 - Typical Transfer Characteristics

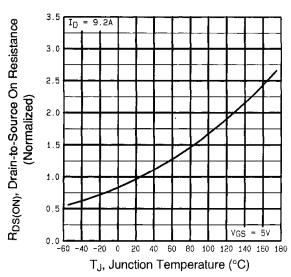


Fig. 4 - Normalized On-Resistance vs. Temperature



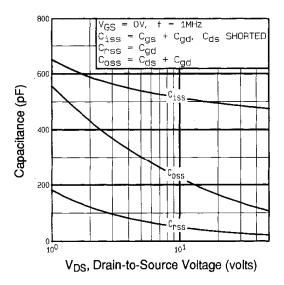


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

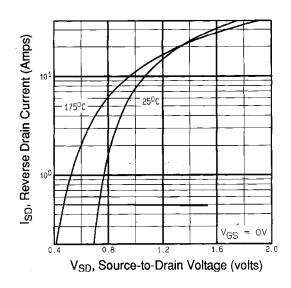


Fig. 7 - Typical Source-Drain Diode Forward Voltage

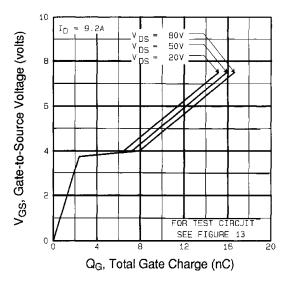


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

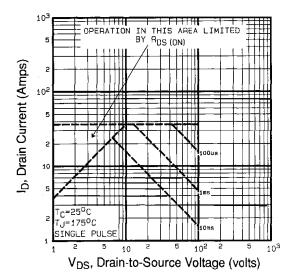


Fig. 8 - Maximum Safe Operating Area





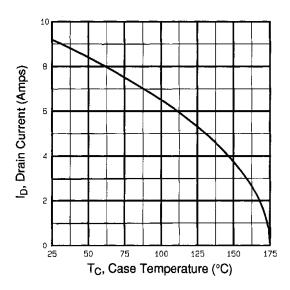


Fig. 9 - Maximum Safe Operating Area

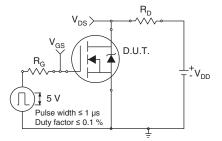


Fig. 10a - Switching Time Test Circuit

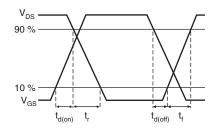


Fig. 10b - Switching Time Waveforms

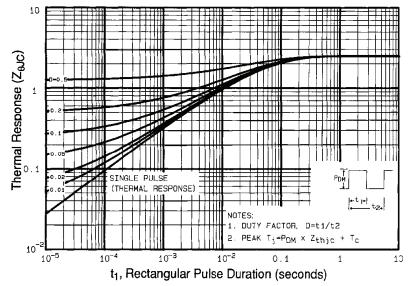
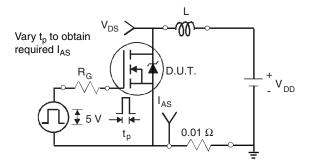


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case





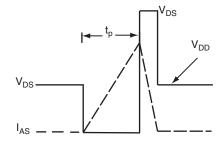


Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

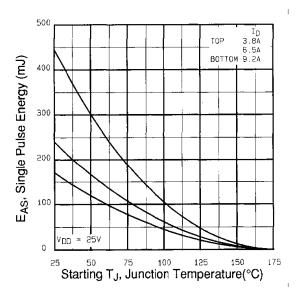


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

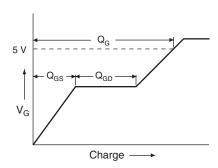


Fig. 13a - Basic Gate Charge Waveform

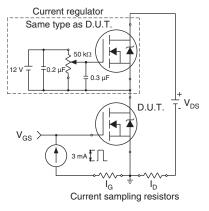
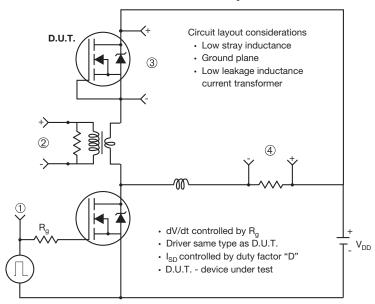


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



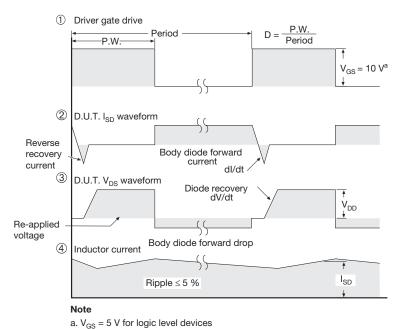


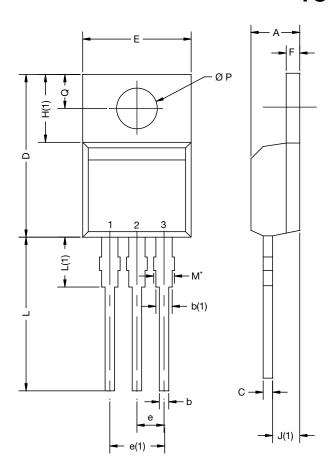
Fig. 14 - For N-Channel

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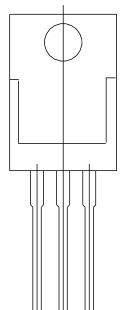
TO-220-1



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.14	4.70	0.163	0.185	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.73	0.045	0.068	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	0.43	1.40	0.017	0.055	
H(1)	6.10	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØΡ	3.53	3.94	0.139	0.155	
Q	2.59	3.00	0.102	0.118	
ECN: X15-0003-Rev. A, 19-Jan-15 DWG: 6031					

Notes

- M* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM
- Outline conforms to JEDEC[®] outline TO-220AB with exception of dimension F



Revison: 19-Jan-15 1 Document Number: 66542



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Vishay

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Revision: 02-Oct-12 Document Number: 91000

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